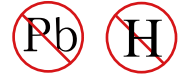




YEA SHIN TECHNOLOGY CO., LTD

YSP2307

# P-Channel Enhancement MOSFET



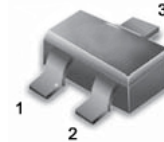
VDS= -16V, ID= -4.3A

## Features

Advanced trench process technology

High Density Cell Design For Ultra Low On-Resistance

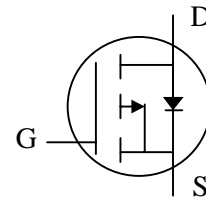
- ▼ Simple Drive Requirement
- ▼ Small Package Outline
- ▼ Surface Mount Device



SOT-23 (TO-236AB)

## MARKING

P07



## PACKAGE INFORMATION

Package	Shipping
SOT-23	3000/Tape&Reel

## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	-16	V
V <sub>GS</sub>	Gate-Source Voltage	±8	V
I <sub>D</sub> @T <sub>A</sub> =25°C	Continuous Drain Current <sup>3</sup>	-4.7	A
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current <sup>3</sup>	-3.3	A
I <sub>DM</sub>	Pulsed Drain Current <sup>1</sup>	-20	A
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation	1.1	W
P <sub>D</sub> @T <sub>A</sub> =70°C	Total Power Dissipation	0.7	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

## Thermal Data

Symbol	Parameter	Value	Unit
R <sub>thj-a</sub>	Thermal Resistance Junction-ambient <sup>3</sup>	110	°C/W

# ELECTRICAL CHARACTERISTICS

## YSP2307

### Electrical Characteristics @ $T_j=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-16	-	-	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=-4.5V, I_D=-4.7A$	-	48	70	$m\Omega$
		$V_{GS}=-2.7V, I_D=-3.8A$	-	63	100	$m\Omega$
		$V_{GS}=-2.5V, I_D=-1.0A$	-	65	110	$m\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.6	-0.85	-1.4	V
$g_{fs}$	Forward Transconductance	$V_{DS}=-10V, I_D=-4.7A$	-	8	-	S
$I_{DSS}$	Drain-Source Leakage Current ( $T_j=25^\circ\text{C}$ )	$V_{DS}=-16V, V_{GS}=0V$	-	-	-1	$\mu A$
$I_{GSS}$	Gate-Source Leakage	$V_{GS}=\pm 8V, V_{DS}=0V$	-	-	$\pm 100$	nA
$Q_g$	Total Gate Charge <sup>2</sup>	$I_D=-4.7A$	-	24	36	nC
$Q_{gs}$	Gate-Source Charge	$V_{DS}=-10V$	-	18	-	nC
$Q_{gd}$	Gate-Drain ("Miller") Charge	$V_{GS}=-4.5V$	-	2.7	-	nC
$t_{d(on)}$	Turn-on Delay Time <sup>2</sup>	$V_{DS}=-10V$	-	22	35	ns
$t_r$	Rise Time	$I_D=-1A$	-	35	55	ns
$t_{d(off)}$	Turn-off Delay Time	$R_G=6\Omega, V_{GS}=-4.5V$	-	45	70	ns
$t_f$	Fall Time	$R_D=10\Omega$	-	25	40	ns
$C_{iss}$	Input Capacitance	$V_{GS}=0V$	-	985	1580	pF
$C_{oss}$	Output Capacitance	$V_{DS}=-15V$	-	180	-	pF
$C_{rss}$	Reverse Transfer Capacitance	$f=1.0\text{MHz}$	-	160	-	pF

### Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$I_S$	Max Diode Forward Current				-1.7	A
$V_{SD}$	Diode Forward Voltage	$I_S=-1.7A, V_{GS}=0V$			-1.2	V

#### Notes:

1. Pulse width limited by Max. junction temperature.
2. Pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
3. Surface mounted on 1 in<sup>2</sup> copper pad of FR4 board; 270°C/W when mounted on min. copper pad.

# DEVICE CHARACTERISTICS

## YSP2307

### TYPICAL ELECTRICAL CHARACTERISTICS

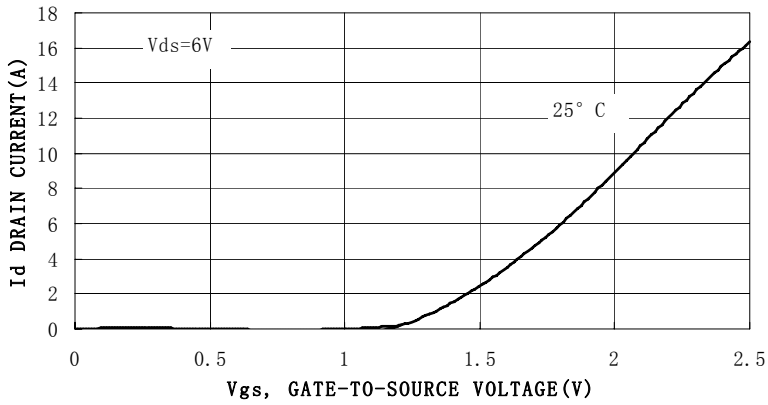


Figure 1. Transfer Characteristics

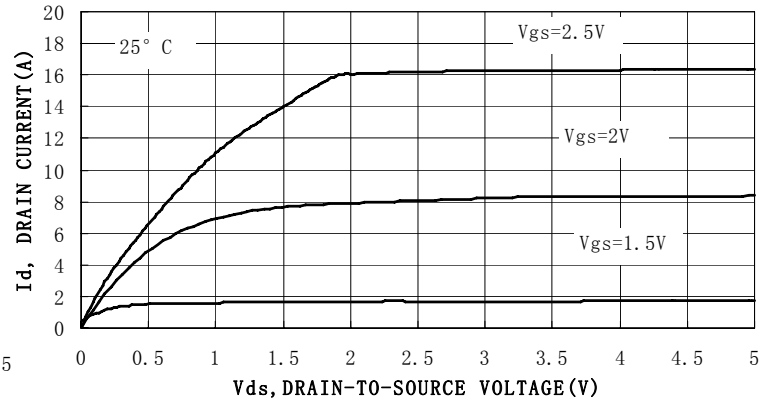


Figure 2. On-Region Characteristics

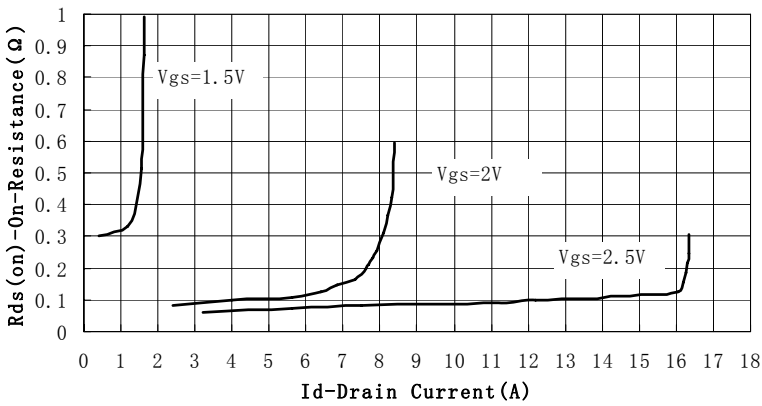


Figure 3. On-Resistance versus Drain Current

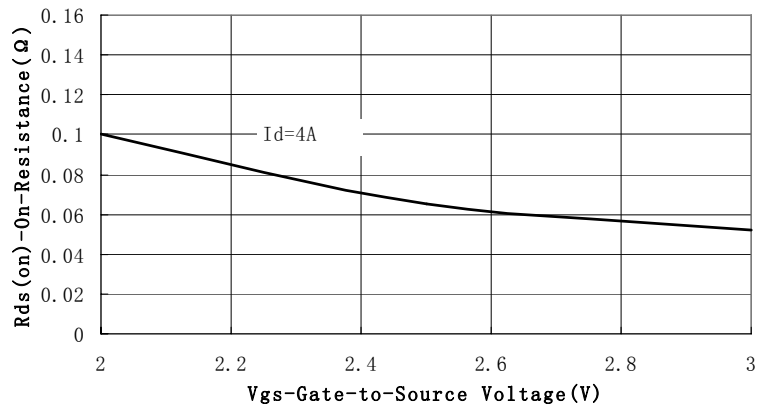


Figure 4. On-Resistance vs. Gate-to-Source Voltage

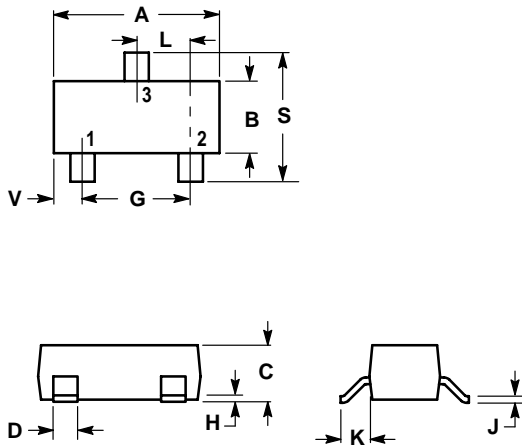
# PACKAGE OUTLINE & DIMENSIONS

## YSP2307

### SOT-23

**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M,1982
2. CONTROLLING DIMENSION: INCH.



DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.1102	0.1197	2.80	3.04
B	0.0472	0.0551	1.20	1.40
C	0.0350	0.0440	0.89	1.11
D	0.0150	0.0200	0.37	0.50
G	0.0701	0.0807	1.78	2.04
H	0.0005	0.0040	0.013	0.100
J	0.0034	0.0070	0.085	0.177
K	0.0140	0.0285	0.35	0.69
L	0.0350	0.0401	0.89	1.02
S	0.0830	0.1039	2.10	2.64
V	0.0177	0.0236	0.45	0.60

